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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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General information

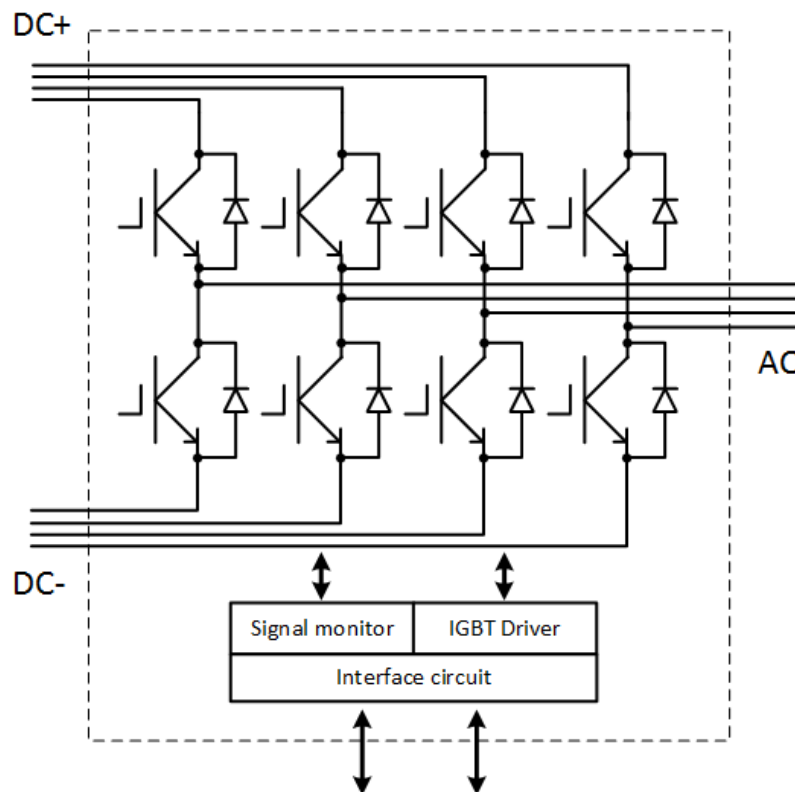
IPM for typical voltages up to 690 V_{RMS}
Rated output current 1550 A_{RMS}

Features

- Integrated current, voltage and temperature measurement
- Tvjop max=150°C
- Real time Tvj simulation
- IGBT4 technology
- Smart protection
- TIM and pressfit technology
- Modbus interface
- 100% tested IPM
- ROHS compliant
- Integrated chip current : 2400A
- Integrated chip voltage: 1700V



Topology	half bridge
Application	Energy Storage, Smart Grid, Wind, Drives, Solar
Heatsink	water cooled
Implemented sensors	voltage, current, temperature
Driver signals IGBT	+15V
Approvals	UL61800-5-1
Sales - name	IFF2400P17LE440988



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Preliminary data

Characteristic values

IGBT characteristic value

			min.	typ.	max.	
Collector-emitter voltage	$I_C = 2400\text{ A}, T_{vj} = 25^\circ\text{C}$	$V_{ce\text{ sat}}$		1.95	2.30	V
	$I_C = 2400\text{ A}, T_{vj} = 150^\circ\text{C}$			2.45		V
Turn on energy loss	$I_C = 2400\text{ A}, V_{DC} = 900\text{ V}, L_S = 17\text{ nH}, T_{vj} = 25^\circ\text{C}$	E_{on}		730		mJ
	$I_C = 2400\text{ A}, V_{DC} = 900\text{ V}, L_S = 17\text{ nH}, T_{vj} = 150^\circ\text{C}$			1170		mJ
Turn off energy loss	$I_C = 2400\text{ A}, V_{DC} = 900\text{ V}, L_S = 17\text{ nH}, T_{vj} = 25^\circ\text{C}$	E_{off}		460		mJ
	$I_C = 2400\text{ A}, V_{DC} = 900\text{ V}, L_S = 17\text{ nH}, T_{vj} = 150^\circ\text{C}$			810		mJ
Thermal resistance junction to ambient for diode due diode housing	per IPM switch, flow rate: 15l/min	$R_{thja\text{ IGBT-<IGBT}}$		0.0254		K/W
Thermal resistance junction to ambient for IGBT due IGBT housing	per IPM switch, flow rate: 15l/min	$R_{thja\text{ IGBT-<diode}}$		0.0135		K/W

Notes

Cooling fluid = 48% water / 52% mono-ethylene glycol,
For further details about the thermal resistance please refer to the handbook.

Diode characteristic value

			min.	typ.	max.	
Forward voltage	$I_C = 2400\text{ A}, T_{vj} = 25^\circ\text{C}$	V_F		1.80	2.20	V
	$I_C = 2400\text{ A}, T_{vj} = 150^\circ\text{C}$			1.95		V
Reverse recovery energy	$I_C = 2400\text{ A}, V_{DC} = 900\text{ V}, L_S = 17\text{ nH}, T_{vj} = 25^\circ\text{C}$	E_{rec}		250		mJ
	$I_C = 2400\text{ A}, V_{DC} = 900\text{ V}, L_S = 17\text{ nH}, T_{vj} = 150^\circ\text{C}$			530		mJ
Thermal resistance junction to ambient for diode due diode housing	per IPM switch, flow rate: 15l/min	$R_{thja\text{ diode-<diode}}$		0.0358		K/W
Thermal resistance junction to ambient for IGBT due IGBT housing	per IPM switch, flow rate: 15l/min	$R_{thja\text{ diode-<IGBT}}$		0.0134		K/W

Notes

Cooling fluid = 48% water / 52% mono-ethylene glycol,
For further details about the thermal resistance please refer to the handbook.

Absolute maximum rated values

Collector-emitter voltage	IGBT; $T_{vj} = 25^\circ\text{C}$	V_{CES}		1700		V
Repetitive peak reverse voltage	Diode; $T_{vj} = 25^\circ\text{C}$	V_{RRM}		1700		V
DC link voltage		V_{DC}		1450		V
Peak switching current		I_{peak}		4000		A
Insulation test voltage	$f = 50\text{ Hz}, t = 60\text{ s}$	V_{ISOL}		3.4		kV _{RMS}
Junction temperature	under switching conditions	T_{vjop}		150		°C
Operational ambient temperature min.		T_{amb}		-40		°C
Switching frequency operation values		f_{sw2}		10		kHz

Notes

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Operation values

			min.	typ.	max.	
Rated continuous current	$V_{DC} = 1100 \text{ V}$, $V_{AC} = 690 \text{ V}_{RMS}$, $\cos(\varphi) = 0.85$, $f_{AC \text{ sine}} = 50 \text{ Hz}$, $f_{sw} = 3000 \text{ Hz}$, $T_{inlet} = 40^\circ\text{C}$, $T_j \leq 150^\circ\text{C}$	I_{AC}		1550		A_{RMS}
Power losses	$I_{AC} = 1550 \text{ A}$, $V_{DC} = 1100 \text{ V}$, $V_{AC} = 690 \text{ V}_{RMS}$, $\cos(\varphi) = 0.85$, $f_{AC \text{ sine}} = 50 \text{ Hz}$, $f_{sw} = 3000 \text{ Hz}$, $T_{inlet} = 40^\circ\text{C}$, $T_j \leq 150^\circ\text{C}$	P_{loss}		8900		W

Controller interface

			min.	typ.	max.	
Auxiliary voltage		V_{aux}	19.2	24	28.3	V
Auxiliary power requirement	$V_{aux} = 24 \text{ V}$	P_{aux}			48	W
Digital input level		$V_{in \text{ low}}$			2	V
		$V_{in \text{ high}}$	8.5		16	V
Digital output level	max. 1 mA	$V_{out \text{ low}}$			2	V
		$V_{out \text{ high}}$	13.5	15	16.5	V
Interlock time	default value	$t_{interlock}$		4		μs
Propagation delay for PWM	default value	t_{prop}		4		μs
Analog output for phase current	for 1550A	$V_{Iac \text{ ana}}$		3.69		V
Over current shut down	default value, response time 15 μs	$I_{ac \text{ trip}}$		4200		A
Analog DC link voltage sensor output	load max 5 mA, @ 1100 V	$V_{DC \text{ ana}}$		7.86		V
Over voltage shut down	default value, response time 500 μs	$V_{dc \text{ trip}}$		1340		V
Chip over temperature shut down	default value, response time 1000 μs	$T_{vj \text{ trip}}$		150		$^\circ\text{C}$
Analog output for junction temperature	for 150 $^\circ\text{C}$	$V_{Tvj \text{ ana}}$		10		V
PCB ambient over temperature shut down	default value, response time 1 s	$T_{pcb \text{ err}}$		85		$^\circ\text{C}$
Serial BUS	Modbus, RS485			19200		Bit/s

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Preliminary data

System data

			min.	typ.	max.	
EMC robustness	according to IEC61800 at named interfaces	power	V _{Burst}		2	kV
		control	V _{Burst}		2	kV
Storage temperature		T _{stor}	-40		85	°C
Operational ambient temperature		T _{op amb}	-40		65	°C
Stray inductance		L _s		8.5		nH
Lead resistance		R _{CC EE}		1.2		mΩ
Impuls test voltage	Power to logic side, acc.IEC 61800-5-1			12		kV
Isolation test voltage	RMS, f = 50 Hz, t = 60 s	V _{ISOL}		3.4		kV
Creepage distance	Power side to heatsink across housing			13		mm
Clearance	Power side to heatsink			8		mm
Protection degree			IP00			
Pollution degree			2			
Dimensions	width x depth x height		215	338	115	mm
Weight				6.1		kg

Notes

Partical discharge test, power side to logic side, according to IEC 61800-5-1, TE > 1920V

Housing CTI > 175

For further details about the system data please refer to the handbook.

Heatsink water cooled

			min.	typ.	max.	
Water flow	according to coolant specification from Infineon	ΔV/Δt		15		dm ³ /min
Water pressure				6	8	bar
Water pressure drop	at 15 dm ³ /min water flow	Δp		120		mbar
Coolant inlet temperature		T _{inlet}	-40		60	°C

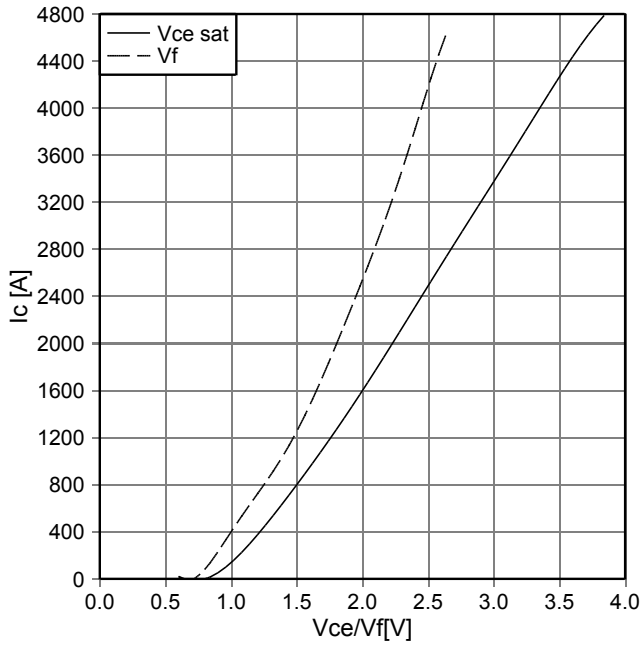
Notes

Cooling fluid = 48% water / 52% mone-ethylene glycol (MEG)

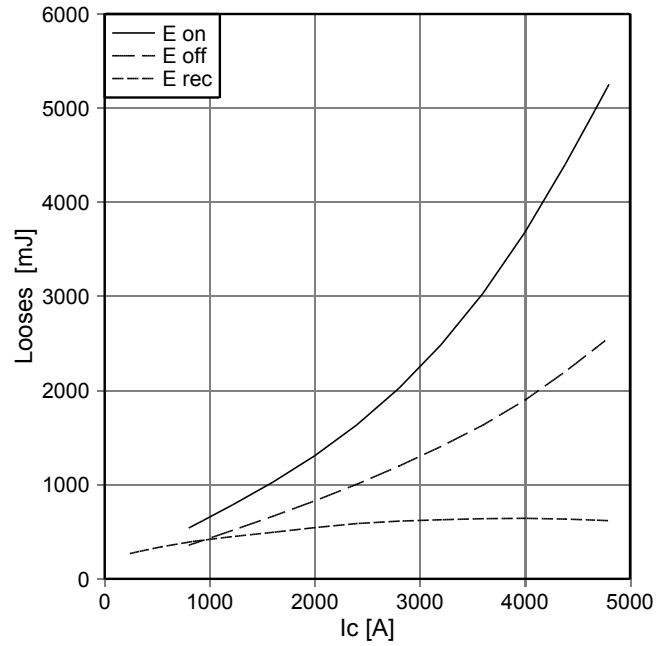
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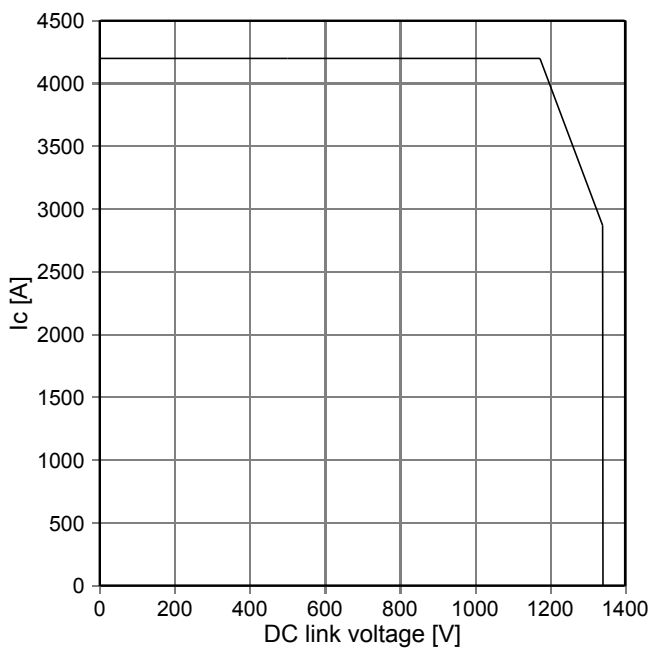
output characteristic IGBT/Diode
 $T_{vj} = 150^{\circ}\text{C}$



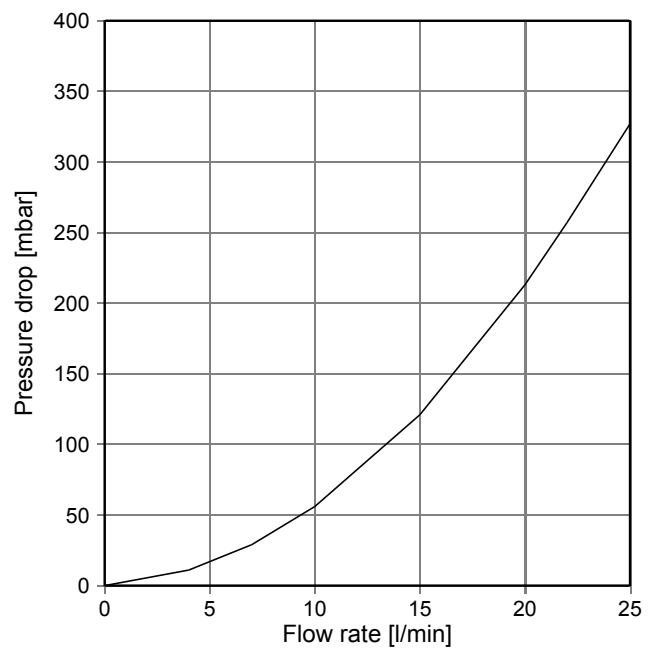
switching losses, Eon, Eoff, Erec
 $V_{dc} 1100\text{V}, T_{vj} = 150^{\circ}\text{C}$



safe operating area



Pressure drop vs. flow rate
 $T_{inlet} = 40^{\circ}\text{C}, 52\% \text{ water} / 48\% \text{ MEG}$

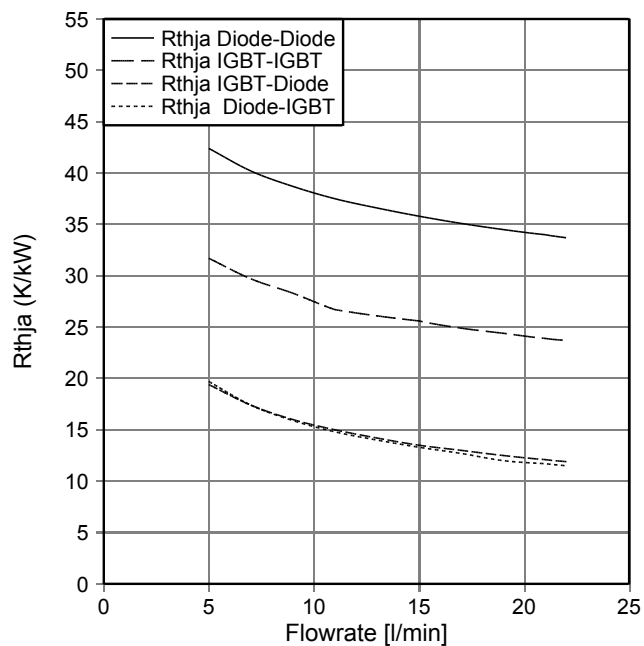


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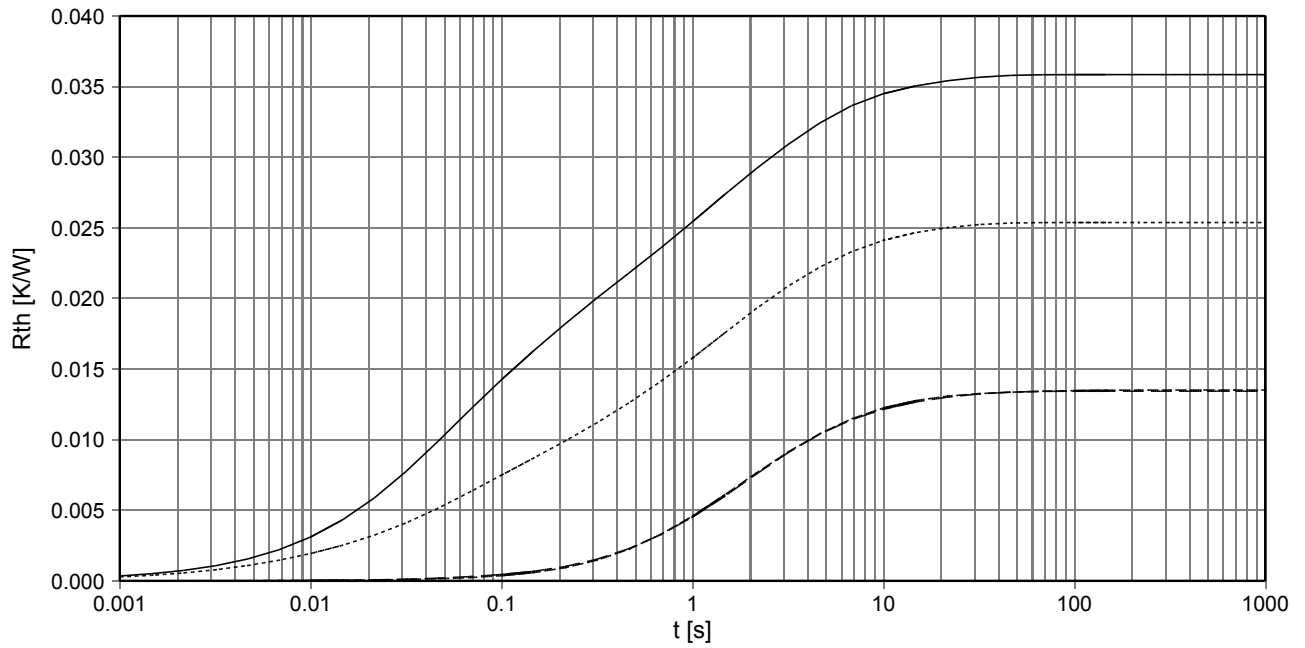
Preliminary data

Thermal resistance vs. Flow rate
T inlet=40°C, 48% water/ 52% MEG



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thermal impedance
 Tinlet =40°C, 48% water/52% MEG, 15l/min



—— Rthja Diode - Diode

i:	1	2	3	4	5	6
r _i [K/W]:	0.00115	0.00737	0.00818	0.0068	0.00975	0.0026
τ _i [s]:	0.032	0.032	0.1165	0.625	2.615	12.1

- - - Rthja IGBT - IGBT

i:	1	2	3	4	5	6
r _i [K/W]:	-0.00085	0.00117	-0.00067	0.00595	0.00565	0.00218
τ _i [s]:	0.024	0.0313	0.084	1.29	3.25	13

- · - - Rthja IGB -Diode

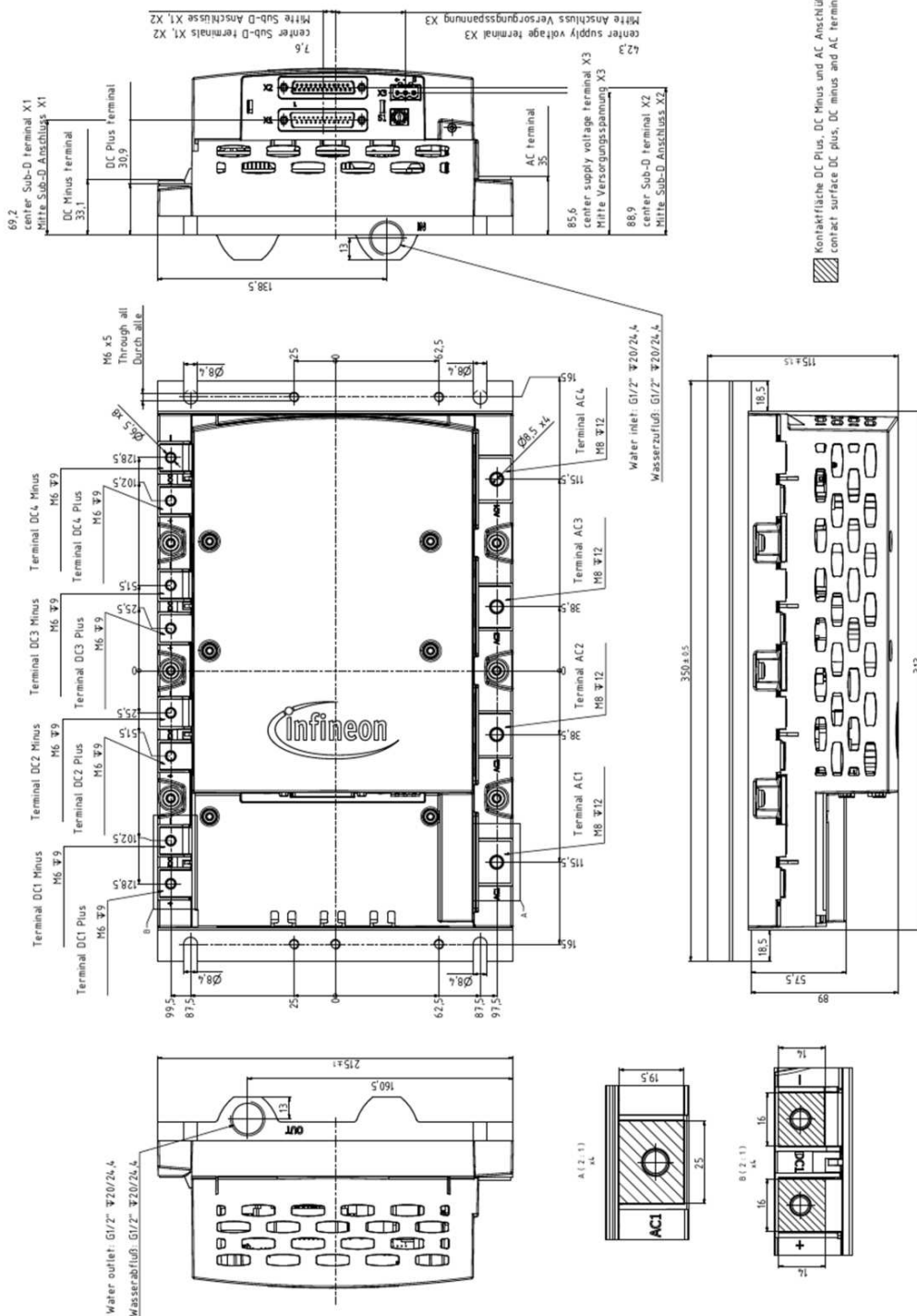
i:	1	2	3	4	5	6
r _i [K/W]:	-0.001	0.00035	0.00491	0.00605	0.00275	0.00045
τ _i [s]:	0.166	0.26	1.025	2.765	7.695	40.84

· · · · · Rthja Diode-IGBT

i:	1	2	3	4	5	6
r _i [K/W]:	0.0008	0.0046	0.003565	0.006735	0.007075	0.0026
τ _i [s]:	0.0053	0.043	0.173	0.897	2.89	10.9

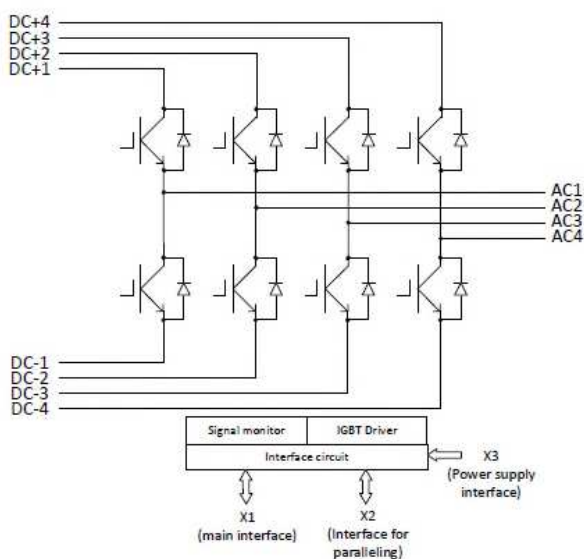
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Mechanical drawing



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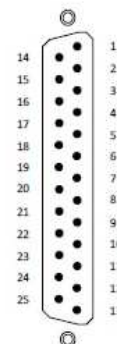
Circuit diagram



Pin configuration for X1 (main control interface)

Pin	Signal	I/O	Pin	Signal	I/O
1	24V_supply	PWR	14	GND_supply	PWR
2	24V_supply	PWR	15	GND_supply	PWR
3	+15_DC	PWR	16	GND_DC	PWR
4	Alert	OUT	17	Enable	IN
5	Fault	IN/OUT	18	Warn_OV	IN/OUT
6	ANA_Tj	ANA OUT	19	ID_det	IN/OUT
7	ANA_Vdc	ANA OUT	20	GND_ana	PWR
8	PWM_top	IN	21	PWM_bot	IN
9	Warn_OC	IN/OUT	22	GND_dig	PWR
10	ANA_ic	ANA OUT	23	Warn_OT	IN/OUT
11	TX/RX_IN+	IN/OUT	24	TX/RX_IN-	IN/OUT
12	TX/RX_Out+	IN/OUT	25	TX/RX_Out-	IN/OUT
13	Shield			Housing is shield	

Detail information for X1, X2 and X3 refer to handbook



Sub-D 25, male with UNC thread

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